



A Product Line of  
Diodes Incorporated



# SPECIFICATION FOR APPROVAL

CUSTOMER \_\_\_\_\_

NOMINAL FREQUENCY \_\_\_\_\_ 16.000000 MHz \_\_\_\_\_

PRODUCT TYPE \_\_\_\_\_ **TYPE FH 2.5x2.0 SEAM SEALED CRYSTAL** \_\_\_\_\_

SPEC. NO. ( P/N ) \_\_\_\_\_ FH1600086Q \_\_\_\_\_

CUSTOMER P/N \_\_\_\_\_

ISSUE DATE \_\_\_\_\_ August 29, 2018 \_\_\_\_\_

VERSION \_\_\_\_\_ B \_\_\_\_\_

APPROVED	PREPARED	QA
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## Diodes Incorporated

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- \*Pb-free
- \*RoHS Compliant
- \*HF-Halogen Free
- \*REACH Compliant
- \*AEC-Q200 Compliant



# TYPE FH 2.5x2.0 SEAM SEALED CRYSTAL

## FH1600086Q

VER. B 29-Aug-18

### ELECTRICAL SPECIFICATIONS

Item	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	16.000000	MHz	
Mode of Oscillation	MO	AT Cut-Fundamental		
Calibration Load Capacitance	CL	8	pF	
Calibration Tolerance	FL	±50	ppm	at 25°C±3°C
Operating Temperature Range	TR	-40 to +125	°C	
Frequency Stability (Frequency Deviation over the Operating Temperature Range)	F/T	±150	ppm	Reference to the Frequency at 25°C
Operating Drive Level		10	μW	
Maximum Drive Level		100	μW	
Equivalent Series Resistance	ESR	120	Ω	Max
Shunt Capacitance	C0	5	pF	Max
Aging at 25°C		±3	ppm	Max, 1st year
Storage Temperature		-55 to +125	°C	
Insulation Resistance		500	MΩ	Min

※ This product doesn't include harmful substance that stipulated by SONY SS-00259 Level 1 and S-AT2-001 Level 1 standard. RoHS Compliant (Pb - Free).

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## AEC-Q200 RELIABILITY TEST SPECIFICATIONS:

### 1. Initial

- 1.1 Physical Dimensions: JESD22, Method JB1-100
- 1.2 External Visual: MIL-STD-883, Method 2009
- 1.3 Freq. Vs. Temperature: Per Specification/Datasheet

### 2. Mechanical

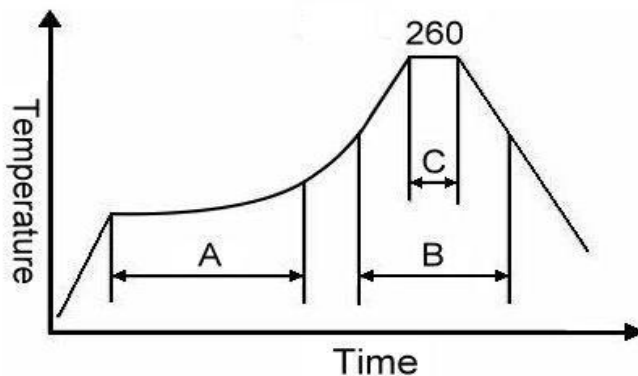
- 2.1 Mechanical Shock: MIL-STD-202 Method 213
- 2.2 Vibration: MIL-STD-202 Method 204
- 2.3 Solderability: J-STD-002
- 2.4 Board Flex: AEC Q200-005
- 2.5 Terminal Strength (SMD): AEC Q200-006

### 3.Environmental

- 3.1 Temp Cycle: JESD22, Method JA-104
- 3.2 Resistance to Solder Heat: MIL-STD-202 Method 210
- 3.3 High Temperature Operating Life: MIL-STD-202, Method 108
- 3.4 High Temp Exposure: MIL-STD-202, Method 108
- 3.5 High Temp & High Humidity: MIL-STD-202, Method 103
- 3.6 Thermal Shock: MIL-STD-202, Method 107

## SUGGESTED IR REFLOW PROFILE

\*As per IPC-JEDEC J-STD-020D



Note:

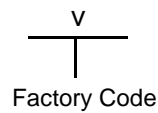
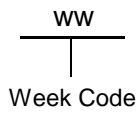
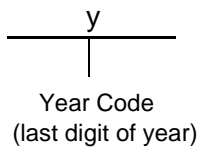
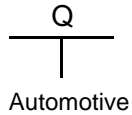
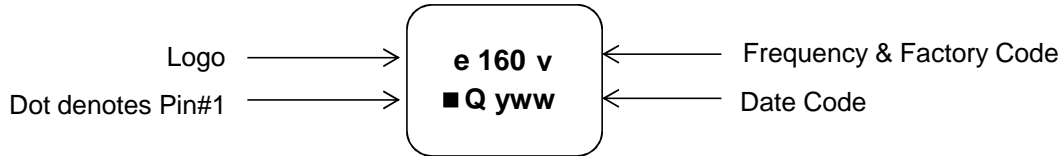
	Stage	Temperature	Time
A	Preheat	150~200°C	60~120 Sec
B	Primary Heat	217°C	60~150 Sec
C	Peak	260°C	10 Sec

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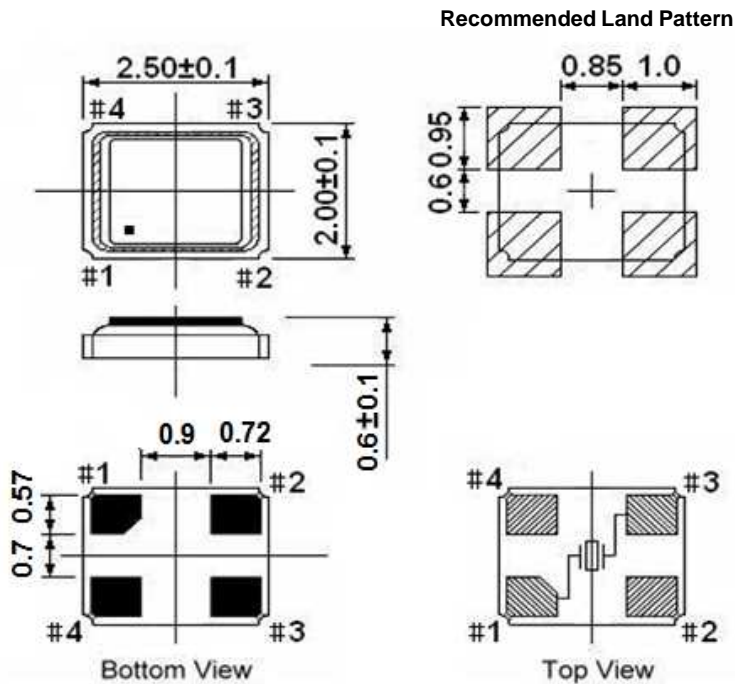
**FH1600086Q**

VER. B 29-Aug-18

## MARKING



## MECHANICAL DRAWINGS ( Scale: None. Dimensions are in mm.)



### Notes:

1. Package drawings are for reference only, and the appearances of objects may vary.  
 Actual packages are based on the real product.
2. The marking dot denotes Pin#1.
3. The position and shape of the chamfer pin may vary and are based on the real product.



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## PACKING

